

(0.80 mm) .0315"

QTE SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QTE

Insulator Material:

Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating: Au or Sn over 50 μ " (1.27 μ m) Ni

Current Rating:

Contact:

2 A per pin

(1 pin powered per row)

Ground Plane:

23 A per ground plane

(1 ground plane powered)

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

225 VAC mated with QSE

& 5 mm Stack Height

Max Cycles: 100

RoHS Compliant: Yes

Board Mates:

QSE

Cable Mates:

EQCD, EQDP

(See Also Available Note)

Standoffs:

SO

QTE-014-01-F-D-DP-A

QTE-040-01-L-D-A

QTE-060-01-L-D-A

Integral metal plane
for power or ground

Standard stack heights
from 5 mm to 25 mm

HIGH-SPEED CHANNEL PERFORMANCE

QTE-DP/QSE-DP @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

28
Gbps



PROCESSING

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (-020-060)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

FILE NO. 090871_0_000

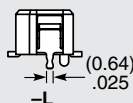
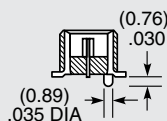
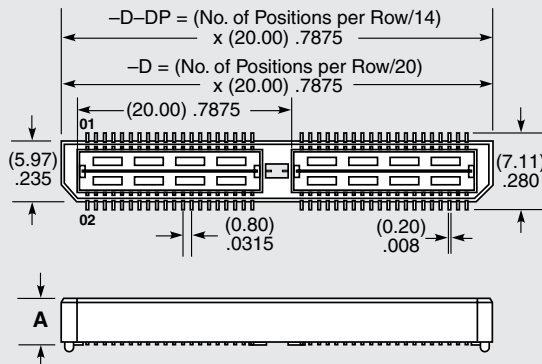
PROTOCOLS

- 100 GbE
- XAUI
- PCI Express®
- SATA
- MGT (Rocket I/O)
- InfiniBand™

ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
 - 30 μ " (0.76 μ m) Gold (Specify -H plating for Data Rate cable mating applications.)
 - Edge Mount, Guide Posts, Screw Down & Friction Lock
 - 56 (-DP), 80, 100 positions per row
 - Retention Option
- Contact Samtec.

QTE	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-020, -040, -060 (40 total pins per bank = -D)	Specify LEAD STYLE from chart	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails	-D = Single-Ended		-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad
	-014, -028, -042 (14 pairs per bank = -D-DP)		-L = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane, Matte Tin on tails	-D-DP = Differential Pair (-01 only)		-TR = Tape & Reel Packaging (N/A -05 & -07 lead style)
			-C* = Electro-Polished Selective 50 μ " (1.27 μ m) min Au over 150 μ " (3.81 μ m) Ni on Signal Pins in contact area, 10 μ " (0.25 μ m) min Au over 50 μ " (1.27 μ m) Ni on Ground Plane in contact area, Matte Tin over 50 μ " (1.27 μ m) min Ni on all solder tails			-L = Latching Option (N/A on -042 & -060 positions)



*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Samtec:

[QTE-028-01-C-D-DP-A-K](#) [QTE-040-03-C-D-A-K](#) [QTE-014-01-C-D-DP-A-TR](#)